

Electronic Patent Application Fee Transmittal

Application Number:	10551460
Filing Date:	30-Sep-2005
Title of Invention:	Thermoplastic resin sheet and laminate
First Named Inventor/Applicant Name:	Masaki Matsudo
Filer:	Lee Cheng/Maki Huffman
Attorney Docket Number:	MIY-0207

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	460	460

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				460